



Product Change Notification: CENO-21HJSV886

Date:

26-Dec-2025

Product Category:

16-Bit Microcontrollers, 8-Bit Microcontrollers

Notification Subject:

CCB 8009 Initial Notice: Qualification of MMT as an additional assembly site for selected PIC24F32KA304, PIC24F16KA304, PIC24FV32KA304, PIC24F16KM204, PIC18F57K42, PIC16F15385, PIC16F15386, PIC16F19186, PIC16F19185, PIC18F55K42, PIC18F56K42, PIC18F25K83, PIC18F26K83, PIC18F26K42, PIC16F1773, PIC16F1776, PIC16F1778, PIC18F27K42 and COMP_MCU_DGD_xx device families available in 28 and 48L UQFN (6x6x0.5mm) packages.

Affected CPNs:

[CENO-21HJSV886_Affected_CPN_12262025.pdf](#)

[CENO-21HJSV886_Affected_CPN_12262025.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as an additional assembly site for selected PIC24F32KA304, PIC24F16KA304, PIC24FV32KA304, PIC24F16KM204, PIC18F57K42, PIC16F15385, PIC16F15386, PIC16F19186, PIC16F19185, PIC18F55K42, PIC18F56K42, PIC18F25K83, PIC18F26K83, PIC18F26K42, PIC16F1773, PIC16F1776, PIC16F1778, PIC18F27K42 and COMP_MCU_DGD_xx device families available in 28 and 48L UQFN (6x6x0.5mm) packages.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)

Assembly Site	UTAC Thai Limited (UTL-1) LTD. (NSEB)		UTAC Thai Limited (UTL-1) LTD. (NSEB)		Microchip Technology Thailand (Branch) (MMT)	Yes
Wire Material	Au		Au		CuPdAu	Yes
Die Attach Material	8600 (PFAS)		8600 (PFAS)		QMI519 (PFAS Free)	Yes
Molding Compound Material	G700LTD		G700LTD		G700LTD	No
Lead-Frame Material	EFTEC-64T	C19 4	EFTEC-64T	C19 4	EFTEC-64T	No
Lead-Lock	Dimple		Dimple		Half Etched	Yes
	See Pre and Post Change for comparison.					

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: March 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	December 2025					>	March 2026				
Work Week	49	50	51	52	01		10	11	12	13	14
Initial PCN Issue Date				X							

Qual Report Availability										X	
Final PCN Issue Date										X	

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:

December 26, 2025: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CENO-21HJSV886 Pre and Post Change Summary.pdf
PFAS Elimination and Die Attach_Explanation.pdf
PCN_CENO-21HJSV886_Qual Plan.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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